PC Web Site for Information on IPC-1752 Standard http://www.ipc.org/IPC-175x Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information	IPC ASSOCIATION CONNECTION ELECTRONICS INDUSTRIE	© Copyright 2005. I	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
Company name* Compan	752-21.1										als and Mfg	Informat	tion		
Inter Name Title - Contact Product Envisor Title - Representative Title - Representative Product Envisor Compliance Requester Item Number Mfr Item Number Mfr Item Number Mfr Item Name Effective Date Version DF08S2 100V 2A BRIDGE SDIP DF08S2 100V 2A BRIDGE SDIP DF08S2 Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Max Grid Array Material Number of Reflow Cycles Terminal Plating / Grid Array Material Terminal Plating / Gri	upplier Inform	nation													
Title - Contact Name Product Envi* Compliance NA Product Envi* Compliance NA Product Envi* Compliance NA Product Envi* Compliance NA Product-Env-Stewards @onsemi.com withorized Representative* Product-Env-Stewards Product Envi* Compliance NA Product-Env-Stewards Product Envi* Compliance NA Product-Env-Stewards Product-Env-Stewards Na Product-Env-Stewards Na Product-Env-Stewards Na Nanufacturing Site Version Manufacturing Site Weight* UOM Annufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Base Alloy Nate Tin (Sn) - annealed OU Alloy 1 STD-020 MSL Rating Peak Process Body Temperature Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Na Nanufacturing Process Na Nanufacturing Site Nanufacturing Site Nanufacturing Site Nanufacturing Site Nanufacturing Site Nanufacturing Site Nanufacturing Nanufacturing Site Nanufacturing Nanufacturing Site Nanufacturing Nanufacturing Site Nanufacturing Proccess Information Nanufacturing Proccess Information Nanufacturing Site	Company name* Company unique ID				ique ID	Unique ID Authority				Response Date*					
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Authorized Representative* Product-Env-Stewards Product Enviro Compliance Requester Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM Manufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Base Alloy Matte Tin (Sn) - annealed Title - Representative Phone - Representative* NA Product-Env-Stewards@onsemi.com Namufacturing Site Weight* UOM Manufacturing Proccess Information Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Seconds Seconds Terminal Plating / Grid Array Material Terminal Base Alloy Terminal Plating / Grid Array Material Terminal Base Alloy Terminal Plating / Grid Array Material Terminal Base Alloy Terminal Plating / Grid Array Material Terminal Base Alloy Terminal Plating / Grid Array Material Terminal Base Alloy Terminal Base All	ontact Name		Title - Contact			I	Phone - Contact*				Email - Contact*				
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		time at neak temperate	ma duning sal	doring is 10.2	O seconds										
or more information regarding material composition please refer to page 3															

RoHS Material Composition Declaration			Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		by mass (100 PPM) in homogeneous material for tum (Cr6+), Polybrominated Biphenyls (PBB), Polyl Disobutyl phthalate (DIBP).							
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and believe as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its uppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier are written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in th									
RoHS Declaration * 4 - Item(s	s) does not contain RoHS restricted substance	ces per the definition above except for selected exer	nptions Supplier Acceptance	* Accepted					
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead). Exemption: 7c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.									
Exemption List Version	EL-2011/534/EU								
Declaration Signature									
Instructions: Complete all of the required in Requester) and click on Submit Form to ha		"Accepted" on the Supplier Acceptance drop-do	wn. This will display the signature area. Digital	lly sign the declaration (if required by the					
Supplier Digital Signature R		,							

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	3.6	mg	Supplier	Silicon (Si)	7440-21-3		3.3768	mg
			В	Nickel (Ni)	7440-02-0		0.0324	mg
			Supplier	Gold (Au)	7440-57-5		0.018	mg
			A	Lead Oxide (PbO)	1317-36-8	7c	0.1728	mg
Die Attach Solder	2.595	mg	Supplier	Silver (Ag)	7440-22-4		0.0649	mg
			A	Lead (Pb)	7439-92-1	7a	2.4004	mg
			Supplier	Tin (Sn)	7440-31-5		0.1297	mg
Lead Frame	63.63	mg	Supplier	Iron (Fe)	7439-89-6		0.0764	mg
			Supplier	Copper (Cu)	7440-50-8		63.5346	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0191	mg
Mold Compound-Black	233.175	mg		Metal Hydroxide	proprietary data		8.1611	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		18.654	mg
			Supplier	Carbon Black (C)	1333-86-4		1.1659	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		186.54	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		18.654	mg
Plating	7.0	mg	Supplier	Tin (Sn)	7440-31-5		7	mg